

fastPACK0 H 2nd gen

V23990-P723-F04-01-14

Maximum Ratings / Höchstzulässige Werte
P723-F04 600V/60A

Parameter	Condition	Symbol	Datasheet values max.	Unit
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DC link Capacitor
DC link Kondensator

Max.DC voltage Max. Gleichspannung	T _C =25°C	U _{MAX}	500	V
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Transistor H-bridge(IGBT)
Transistor H-Brücke(IGBT)

Collector-emitter break down voltage Kollektor-Emitter-Sperrspannung		V _{CE}	600	V
DC collector current Kollektor-Dauergleichstrom	T _j =T _{jmax} Th=80°C, T _C =80°C	I _C	35	A
Repetitive peak collector current Periodischer Kollektorspitzenstrom	tp limited by T _j max	I _{Cpuls}	224	A
Power dissipation per IGBT Verlustleistung pro IGBT	T _j =T _{jmax} Th=80°C T _C =80°C	P _{tot}	93	W
Gate-emitter peak voltage Gate-Emitter-Spitzenspannung		V _{GE}	±20	V
SC withstand time* Kurzschlußverhalten*	T _j =T _{jmax} V _{GE} =15V V _{CC} =360V	t _{SC}	6	us
max. Chip temperature max. Chiptemperatur		T _{jmax}	150	°C

Diode H-bridge
Diode H-Brücke

DC forward current Dauergleichstrom	T _j =T _{jmax} Th=80°C, T _C =80°C	I _F	34	A
Repetitive peak forward current Periodischer Spitzenstrom	tp limited by T _j max	I _{FRM}	150	A
Power dissipation per Diode Verlustleistung pro Diode	T _j =T _{jmax} Th=80°C T _C =80°C	P _{tot}	47	W
max. Chip temperature max. Chiptemperatur		T _{jmax}	150	°C

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Parameter	Condition	Symbol	Datasheet values max.	Unit
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Thermal properties
Thermische Eigenschaften

Storage temperature Lagertemperatur		T_{stg}	-40...+125	°C
Operation temperature Betriebstemperatur		T_{op}	-40...+125	°C

Insulation properties
Modulisation

Insulation voltage Isolationsspannung	t=1min	V_{is}	4000	Vdc
Creepage distance Kriechstrecke			min 12,7	mm
Clearance Luftstrecke			min 12,7	mm

Additional notes and remarks:

* Allowed number of short circuits must be less than 1000 times,
and time duration between short circuits should be more than 1
second!

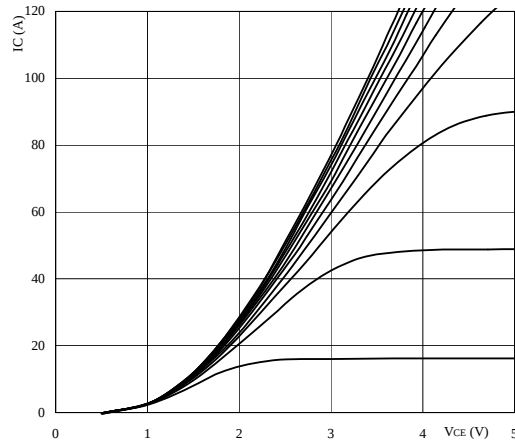
fastPACK V H 2nd gen

V23990-P723-F04-01-14

Characteristic values/ Charakteristische Werte											P723-F04		
Description	Symbol	Conditions					Datasheet values			Unit			
		T(C°)	Other conditions (Rgon-Rgoff)	VGE(V) VGS(V)	VCE(V) VDS(V)	IC(A) IF(A) Id(A)	Min	Typ	Max				
Capacitor													
Kondensator													
C value	C							216	270	324	nF		
C Wert													
Transistor H-bridge(IGBT)													
Transistor H-Brücke(IGBT)													
Gate emitter threshold voltage Gate-Schwellenspannung	V _{GE(th)}	T _J =25°C T _J =125°C	VCE=VGE				0.6m	3	4	5	V		
Collector-emitter saturation voltage Kollektor-Emitter Sättigungsspannung	V _{CE(sat)}	T _J =25°C T _J =125°C		15		60			2,7 3,22	3,7	V		
Collector-emitter cut-off Kollektor-Emitter Reststrom	I _{CES}	T _J =25°C T _J =125°C		0	600					0,35	mA		
Gate-emitter leakage current Gate-Emitter Reststrom	I _{GES}	T _J =25°C T _J =125°C		20	0					300	nA		
Integrated Gate resistor Integrierter Gate Widerstand	R _{gint}								none		Ω		
Turn-on delay time Einschaltverzögerungszeit	t _{d(on)}	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			18		ns		
Rise time Anstiegszeit	t _r	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			16		ns		
Turn-off delay time Abschaltverzögerungszeit	t _{d(off)}	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			206		ns		
Fall time Fallzeit	t _f	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			12		ns		
Turn-on energy loss per pulse Einschaltverlustenergie pro Puls	E _{on}	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			1,1		mWs		
Turn-off energy loss per pulse Abschaltverlustenergie pro Puls	E _{off}	T _J =25°C T _J =125°C	Rgoff=2 Ω Rgon=4 Ω	15	400	60			0,96		mWs		
Input capacitance Eingangskapazität	C _{ies}	T _J =25°C T _J =125°C	f=1MHz	0	25				3		nF		
Output capacitance Ausgangskapazität	C _{oss}	T _J =25°C T _J =125°C	f=1MHz	0	25				0,3		nF		
Reverse transfer capacitance Rückwirkungskapazität	C _{ies}	T _J =25°C T _J =125°C	f=1MHz	0	25				0,18		nF		
Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip	R _{thJH}		Thermal grease thickness:50um warmeleitpaste Dicke:50um λ = 0,61 W/mK						0,76		K/W		
Diode H-bridge													
Diode H-Brücke													
Diode forward voltage Durchlaßspannung	V _F	T _J =25°C T _J =125°C				60	1,2	1,6 1,56	2,3		V		
Peak reverse recovery current Rückstromspitze	I _{RM}	T _J =25°C T _J =125°C	Rgon=4 Ω	15	400	60			100		A		
Reverse recovery time Sperrverzögerungszeit	t _{rr}	T _J =25°C T _J =125°C	Rgon=4 Ω	15	400	60			126		ns		
Reverse recovered charge Sperrverzögerungsladung	Q _{rr}	T _J =25°C T _J =125°C	Rgon=4 Ω	15	400	60			4,5		uC		
Reverse recovered energy Sperrverzögerungsenergie	E _{rec}	T _J =25°C T _J =125°C	Rgon=4 Ω	15	400	60			1,32		mWs		
Thermal resistance chip to heatsink per chip Wärmewiderstand Chip-Kühlkörper pro Chip	R _{thJH}		Thermal grease thickness						1,49		K/W		
Thermal resistance chip to case per chip Wärmewiderstand Chip-Gehäuse pro Chip	R _{thJC}		WarmeleitpasteDicke:50u										
NTC-Thermistor													
NTC-Widerstand													
Rated resistance Nennwiderstand	R ₂₅	T _J =25°C	Tol. ±5%					20,9	22	23,1	kOhm		
Deviation of R100 Abweichung von R100	D _{R/R}	T _C =100°C	R100=1503Ω						2,9		%/K		
Power dissipation given Epcos-Typ Verlustleistung Epcos-Typ angeben	P	T _J =25°C							210		mW		
B-value B-Wert	B _(25/100)	T _J =25°C	Tol. ±3%						3980		K		

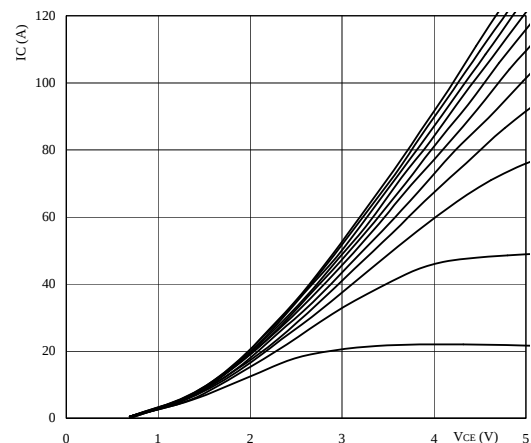
Output inverter

Figure 1. Typical output characteristics
Output inverter IGBT
 $I_C = f(V_{CE})$



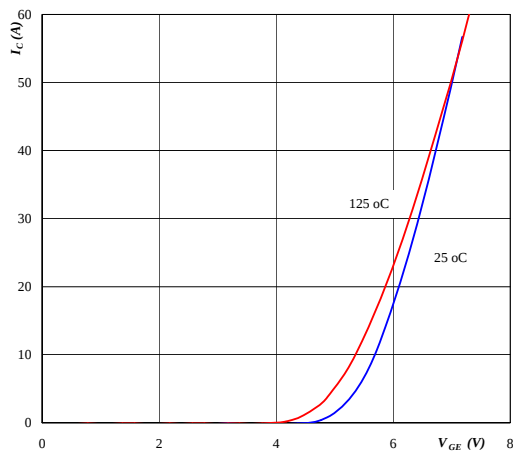
parameter: $t_p = 250 \text{ us}$ $T_j = 25^\circ\text{C}$
V_{GE} parameter: from: 6 V to 16 V
in 1 V steps

Figure 2. Typical output characteristics
Output inverter IGBT
 $I_C = f(V_{CE})$



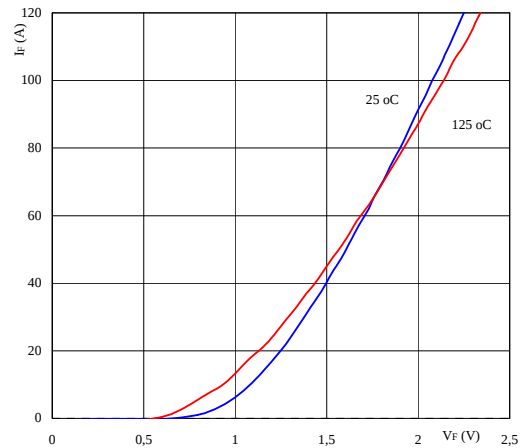
parameter: $t_p = 250 \text{ us}$ $T_j = 125^\circ\text{C}$
V_{GE} parameter: from: 6 V to 16 V
in 1 V steps

Figure 3. Typical transfer characteristics
Output inverter IGBT
 $I_C = f(V_{GE})$



parameter: $t_p = 250 \text{ us}$ $V_{CE} = 10 \text{ V}$

Figure 4. Typical diode forward current as a function of forward voltage
Output inverter FRED $I_F = f(V_F)$



parameter: $t_p = 250 \text{ us}$

Output inverter

Figure 5. Typical switching energy losses as a function of collector current
Output inverter IGBT
 $E = f(I_C)$

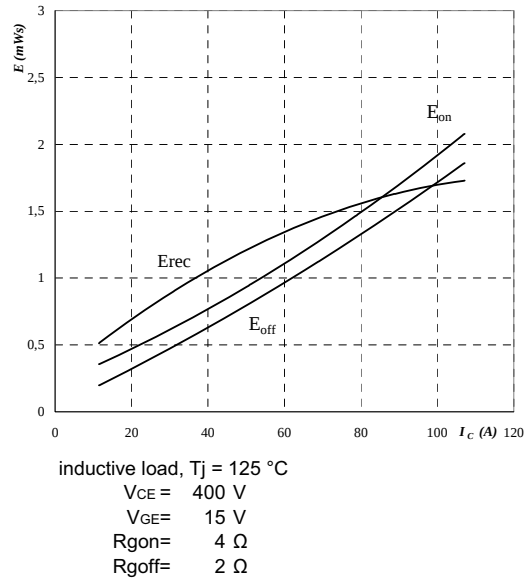


Figure 7. Typical switching times as a function of collector current
Output inverter IGBT
 $t = f(I_C)$

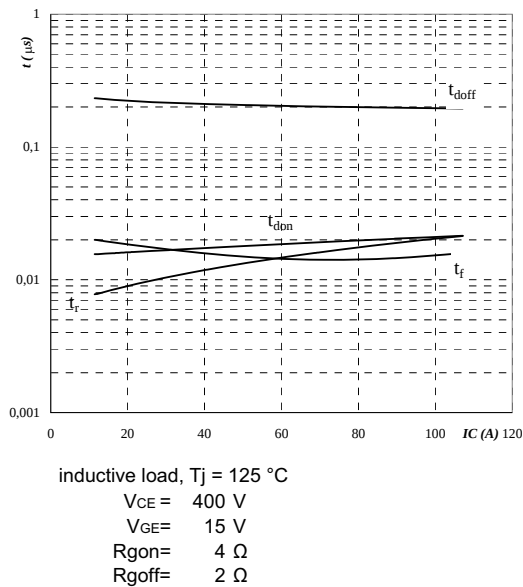


Figure 6. Typical switching energy losses as a function of gate resistor
Output inverter IGBT
 $E = f(R_G)$

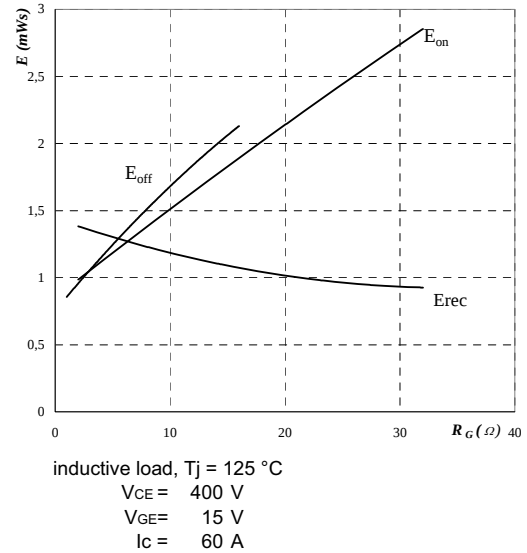
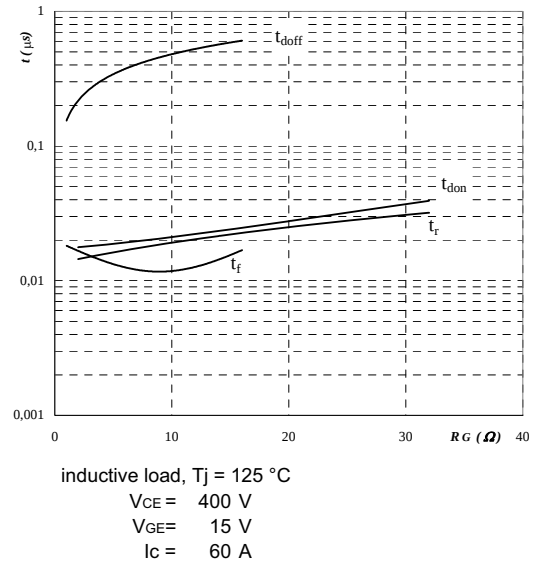


Figure 8. Typical switching times as a function of gate resistor
Output inverter IGBT
 $t = f(R_G)$



Output inverter

Figure 9. Typical reverse recovery time as a function of IGBT turn on gate resistor
Output inverter FRED diode
 $t_{rr} = f(R_{gon})$

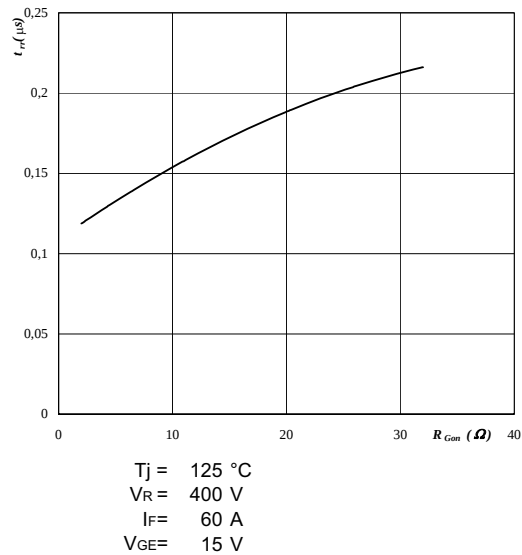


Figure 10. Typical reverse recovery current as a function of IGBT turn on gate resistor
Output inverter FRED diode
 $I_{RRM} = f(R_{gon})$

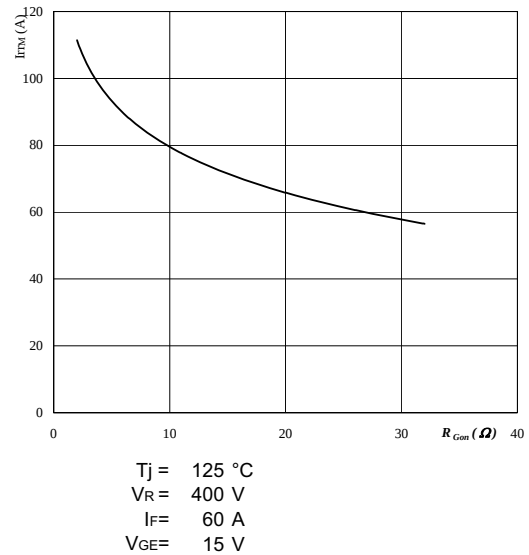


Figure 11. Typical reverse recovery charge as a function of IGBT turn on gate resistor
Output inverter FRED diode
 $Q_{rr} = f(R_{gon})$

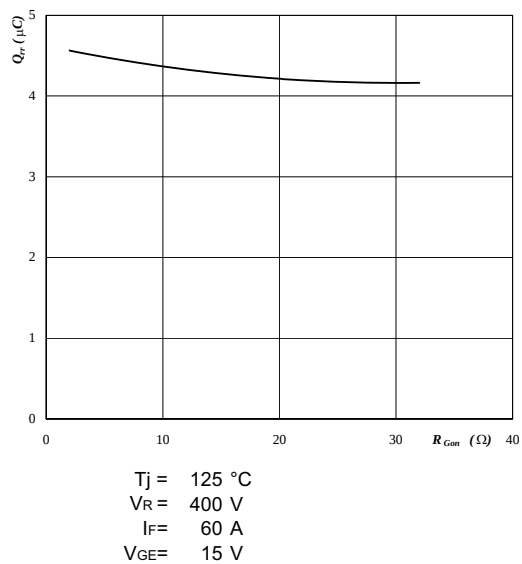
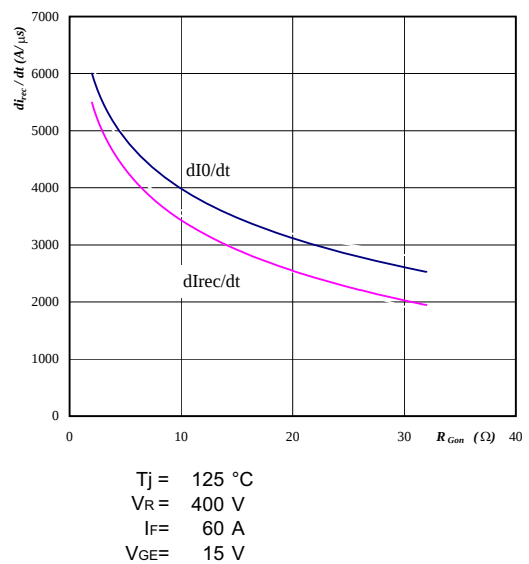
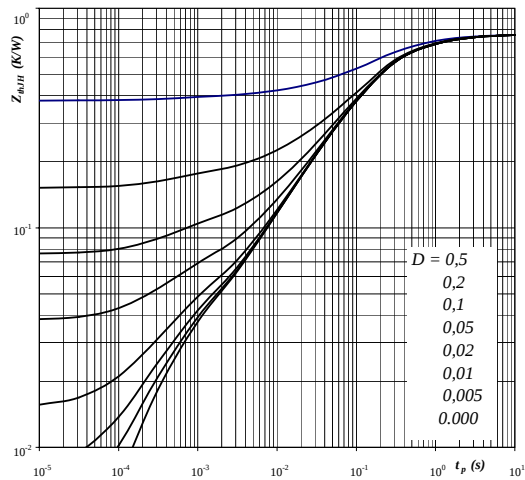


Figure 12. Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor
Output inverter FRED diode
 $dI_0/dt, dI_{rec}/dt = f(R_{gon})$



Output inverter

Figure 13. IGBT transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$

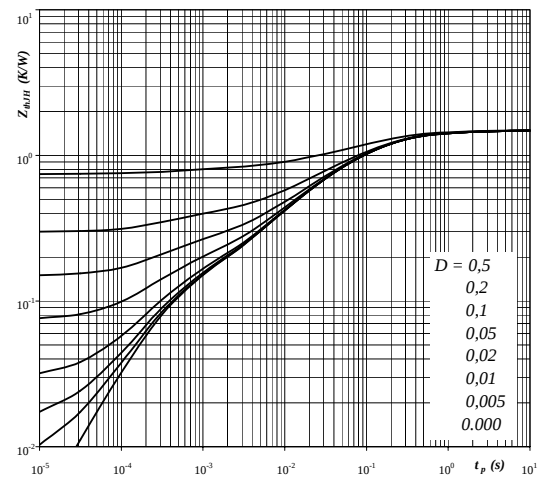


Parameter: $D = t_p / T$ $R_{thJH} = 0,76 \text{ K/W}$

IGBT thermal model values

R (C/W)	Tau (s)
0,04	4,9E+00
0,13	8,8E-01
0,41	1,7E-01
0,12	3,0E-02
0,03	4,9E-03
0,03	4,3E-04

Figure 14. FRED transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$



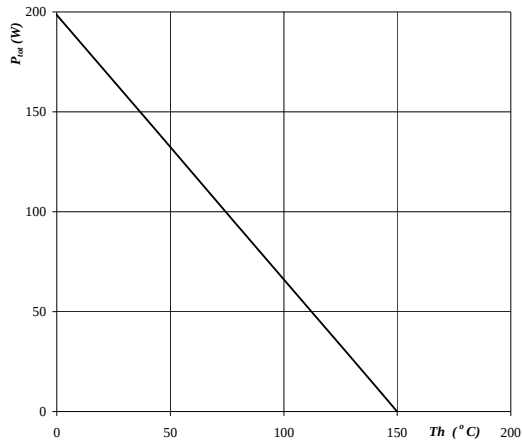
Parameter: $D = t_p / T$ $R_{thJH} = 1,49 \text{ K/W}$

FRED thermal model values

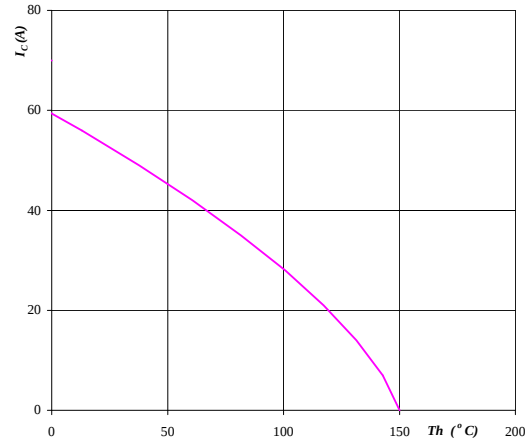
R (C/W)	Tau (s)
0,06	3,8E+00
0,20	5,1E-01
0,62	1,1E-01
0,39	2,2E-02
0,12	3,8E-03
0,10	3,3E-04

Output inverter**Figure 15. Power dissipation as a function of heatsink temperature***Output inverter IGBT*

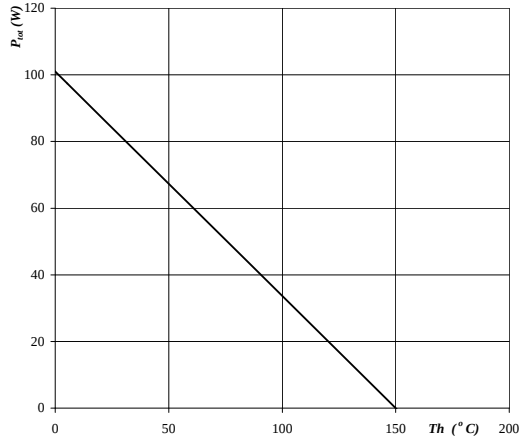
$$P_{tot} = f(T_h)$$

parameter: $T_j = 150^{\circ}C$ **Figure 16. Collector current as a function of heatsink temperature***Output inverter IGBT*

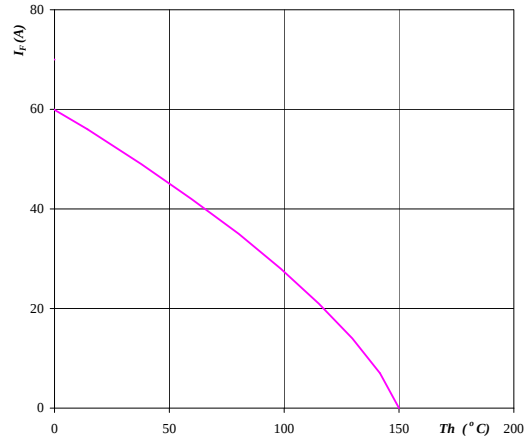
$$I_c = f(T_h)$$

parameter: $T_j = 150^{\circ}C$
 $V_{GE} = 15\text{ V}$ **Figure 17. Power dissipation as a function of heatsink temperature***Output inverter FRED*

$$P_{tot} = f(T_h)$$

parameter: $T_j = 150^{\circ}C$ **Figure 18. Forward current as a function of heatsink temperature***Output inverter FRED*

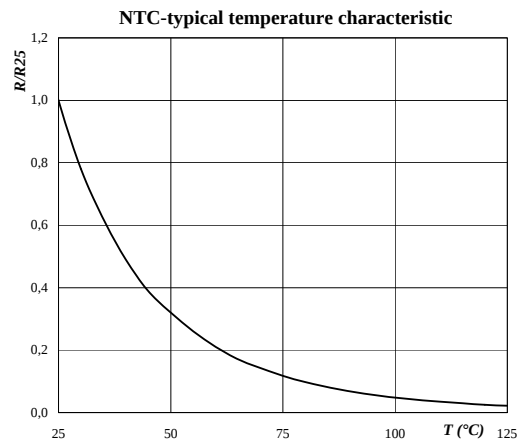
$$I_F = f(T_h)$$

parameter: $T_j = 150^{\circ}C$

Thermistor

**Figure 1. Typical NTC characteristic
as a function of temperature**

$$R_T = f(T)$$

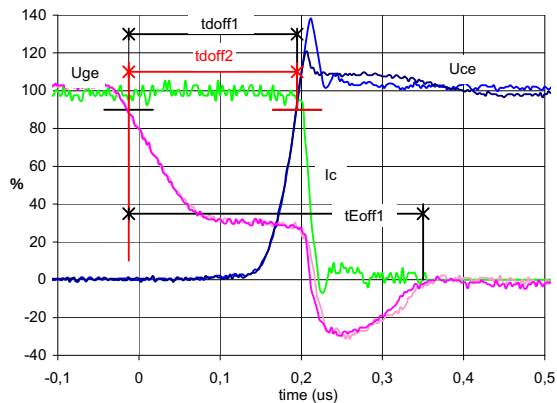


Switching definitions

General conditions: $T_j = 125\text{ °C}$

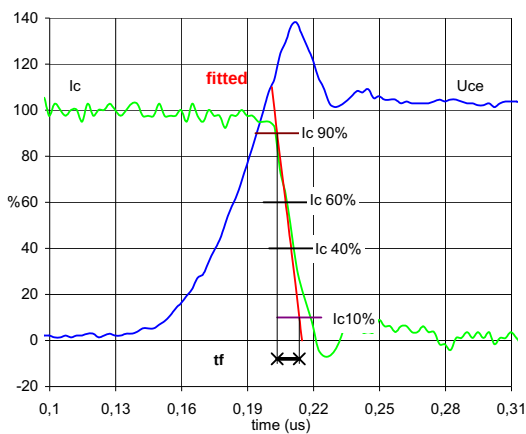
$R_{gon} = 4\text{ }\Omega$ $R_{goff} = 2\text{ }\Omega$

Figure 1. Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})
Output inverter IGBT



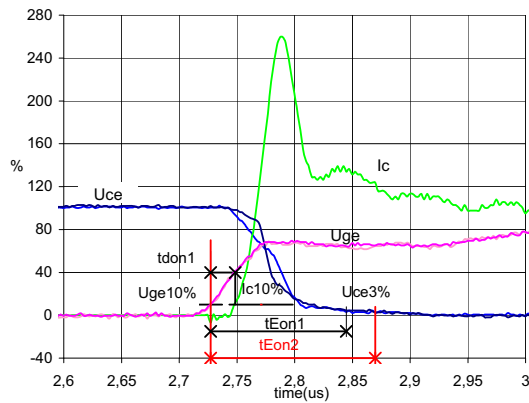
Uge(0%)= 0 V without capacitor (P623-F04)
Uge(100%)= 15 V with capacitor (P723-F04)
Uc(100%)= 400 V
Ic(100%)= 60 A
t_{doff}= 0,21 us
t_{Eoff}= 0,37 us

Figure 3. Turn-off Switching Waveforms & definition of t_f
Output inverter IGBT



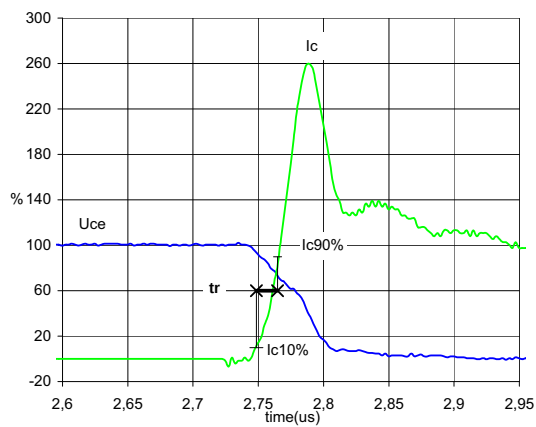
Uc(100%)= 400 V
Ic(100%)= 60 A
t_f= 0,013 us

Figure 2. Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
(t_{Eon} = integrating time for E_{on})
Output inverter IGBT



Uge(0%)= 0 V without capacitor
Uge(100%)= 15 V with capacitor
Uc(100%)= 400 V
Ic(100%)= 60 A
t_{don}= 0,02 us
t_{Eon}= 0,12 us

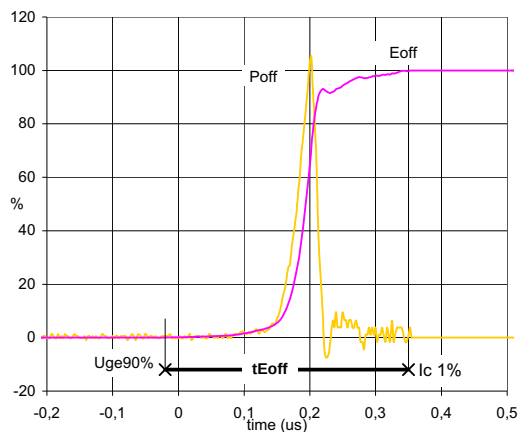
Figure 4. Turn-on Switching Waveforms & definition of t_r
Output inverter IGBT



Uc(100%)= 400 V
Ic(100%)= 60 A
t_r= 0,017 us

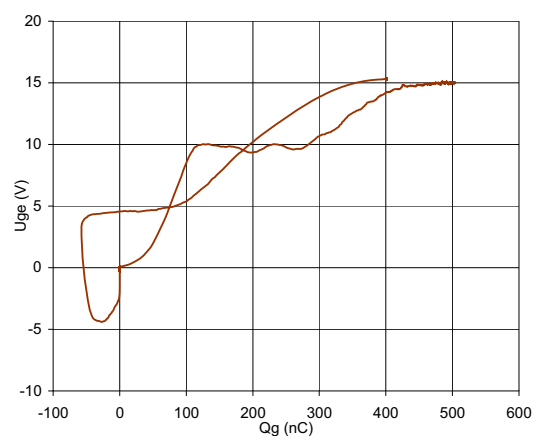
Switching definitions

Figure 5. Turn-off Switching Waveforms & definition of t_{Eoff}
Output inverter IGBT



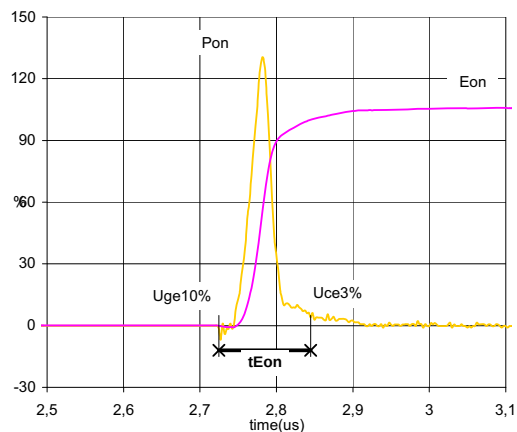
Poff(100%)= 23,96 kW
Eoff(100%)= 0,97 mJ
 t_{Eoff} = 0,37 μ s

Figure 7. Gate voltage vs Gate charge
Output inverter IGBT



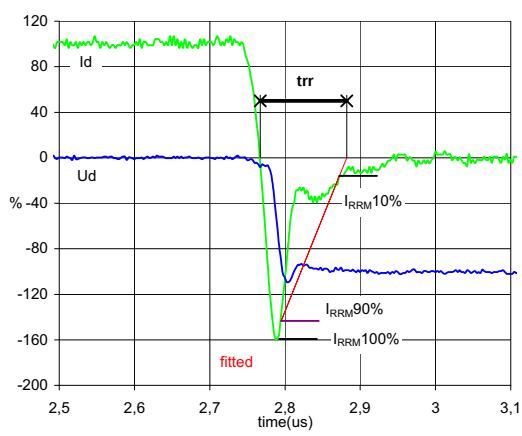
Ugeoff= 0 V
Ugeon= 15 V
Uc(100%)= 400 V
Ic(100%)= 60 A
Qg= 503,8 nC

Figure 6. Turn-on Switching Waveforms & definition of t_{Eon}
Output inverter IGBT



Pon(100%)= 24 kW
Eon(100%)= 1,06 mJ
 t_{Eon} = 0,12 μ s

Figure 8. Turn-off Switching Waveforms & definition of t_{rr}
Output inverter FRED



Ud(100%)= 400 V
Id(100%)= 60 A
 I_{RRM} (100%)= 96 A
 t_{rr} = 0,11 μ s

Switching definitions

Figure 9. Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})
Output inverter FRED

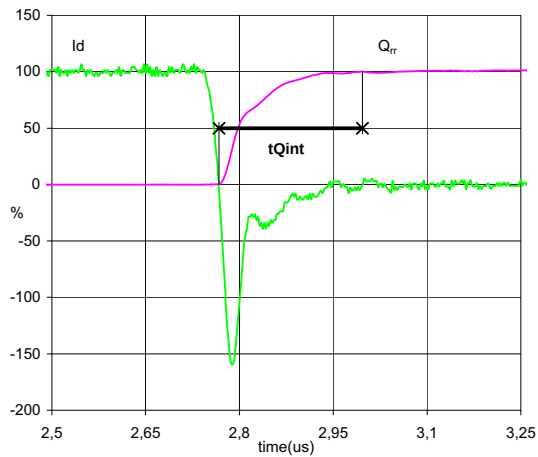


Figure 10. Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})
Output inverter FRED

